

Product / Package Information

Package	LCC
Body Size (mm)	
Lead Count	20
Terminal Finish	Au

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	N/A
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration**Combo Lid**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other Ferrous alloys	Kovar		3.96E-01	92.0	920000	34.76	347602
Nickel & its alloys	Nickel	7440-02-0	1.72E-02	4.00	40000	1.51	15113
Precious metals	Gold	7440-57-5	1.72E-02	4.00	40000	1.51	15113
Subtotal			4.30E-01	100.0	1000000	37.78	377829

Lid Frame

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.59 E-02	79.58	153449	1.40	13985
Tin & its alloys	Tin	7440-31-5	8.78 E-02	20.42	846551	7.72	77153
Subtotal			1.04E-01	100.00	1000000	9.11	91138

Ceramic Package

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Ceramics							
Ceramics	Aluminum oxide	1344-28-1	4.73E-01	90.50	905000	41.52	415173
Ceramics	Chromium oxide	1308-38-9	2.04E-02	3.90	39000	1.79	17891
Ceramics	Silicon Dioxide	14808-60-7	1.83E-02	3.50	35000	1.61	16056
Ceramics	Titanium dioxide	13463-67-7	5.22E-03	1.00	10000	0.46	4588
Ceramics	Calcium oxide	1305-78-8	3.13E-03	0.60	6000	0.28	2753
Ceramics	Magnesium oxide	1309-48-4	2.61E-03	0.50	5000	0.23	2294
Subtotal			5.22 E-01	100.00	1000000	45.88	458754
Pattern							
Other inorganic materials	Tungsten	7440-33-7	2.93 E-02	100.00	1000000	2.57	25745
Nickel Plating							
Nickel & its alloys	Nickel	7440-02-0	3.93 E-03	92.00	850000	0.35	3451
Other inorganic materials	Cobalt	7440-48-4	6.93 E-04	8.00	150000	0.06	609
Subtotal			4.62 E-03	100.00	1000000	0.41	4059
Subtotal			5.56 E-01			48.86	488559

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.34 E-03	100.0	1000000	0.73	7328

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum	7429-90-5	1.00 E-03	100.0	1000000	0.09	879

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.90 E-02	100.0	1000000	1.67	16695

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.60 E-02	80.00	800000	1.41	14059
Other organic materials	Cyanoic acid, ethylenedi-4,1-phenylene ester	47073-92-7	3.90 E-03	19.50	195000	0.34	3427
Other organic materials	4-Nonylphenol, branched	84852-15-3	1.00 E-04	0.50	5000	0.01	88
Subtotal			2.00 E-02	100.0	1000000	1.76	17573

Package Totals			Weight (g)	Percentage (%)	PPM
			1.14 E+00	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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